京鼎精密科技股份有限公司

2026 First Quarter Investor Presentation

2026/06/16

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Agenda

- Company Profile
- Financial Reports
- Business Performance and Outlook
- Q&A

Foxsemicon Integrated Technology, Inc.(Fiti)

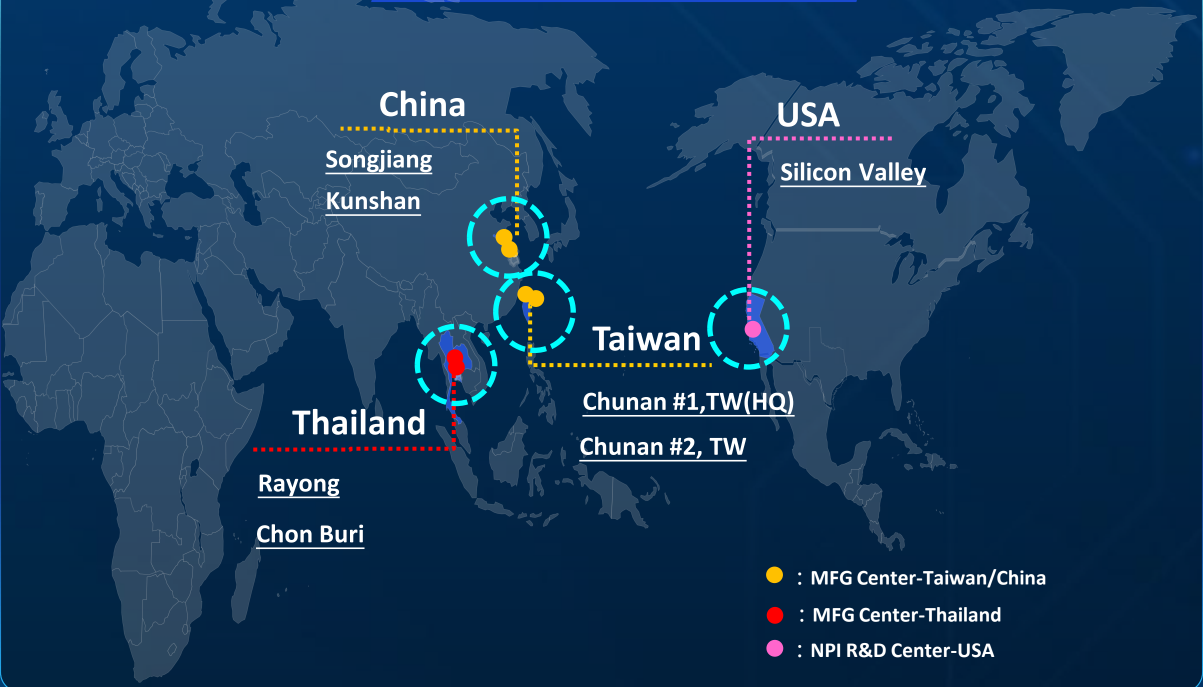
Bob Chen | Chairman

Kevin Chiu | CEO

Business

- Key components and modules for semiconductor front-end equipment manufacturing.
- Semi-related equipment, spares and repair services
- R&D, Sales, and Total solutions provider for semi equipment
- Medical imaging equipment manufacturing and design services.

Global Footprint



2001 Founded

2015 Listed (3413 TT)

4,448 Employees
As of 2026/06/03

NT$1.108 bn Capital
As of 2026/06/03

NT$35.389 bn Market Cap
As of 2026/06/03

1Q26 Revenue	1Q26 Gross Margin	1Q26 EPS
NT$5.562 bn	23.8%	NT$4.28
+14.2% YoY	-3.5 ppt YoY	-36.2% YoY

Global Footprint

Manufacturing Footprint: 7 Sites in 4 Regions

HQ/ HVM Site

Chunan(HQ), TW	Chunan, TW

HVM Site

Songjiang, CN	Kunshan, CN

HVM Site

Rayong, TH	Chonburi, TH

NPI Center

Silicon Valley, USA

Sales & Service Office

San Jose/ Austin/ Phoenix, USA

- ● : HVM Site - Taiwan/ Thailand/ China
- ● : Sales & Service Office - Taiwan/ China/ USA
- ● : NPI R&D Center - USA

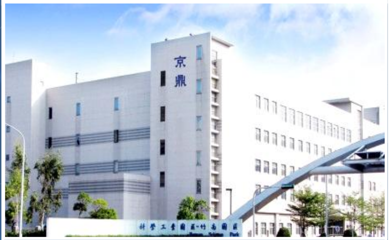
Global Footprint

Manufacturing Footprint: 7 Sites in 4 Regions

HVM Site

Songjiang, CN	Kunshan, CN
	

HQ/ HVM Site

Chunan(HQ), TW	Chunan, TW
	

NPI Center

Silicon Valley, USA


Sales & Service Office

San Jose/ Austin/ Phoenix, USA


HVM Site

Rayong, TH	Chonburi, TH
	

- ●: HVM Site - Taiwan/ Thailand/ China
- ●: Sales & Service Office - Taiwan/ China/ USA
- ●: NPI R&D Center - USA

1Q26 Financial Reports

Statements of Comprehensive Income

(NTD in millions)	1Q26		4Q25		QoQ%	1Q25		YoY%
Revenues	5,562	100.0%	5,227	100.0%	6.4%	4,869	100.0%	14.2%
Gross Profit	1,326	23.8%	1,249	23.9%	-0.1 ppts	1,330	27.3%	-3.5 ppts
Operating expenses	(599)	(10.7%)	(629)	(12.0%)		(453)	(9.3%)	
Operating Income	727	13.1%	620	11.9%	+1.2 ppts	877	18.0%	-4.9 ppts
Non-Operating Items	34	0.6%	169	3.2%		83	1.7%	
Income Before Tax	761	13.7%	791	15.1%	-1.4 ppts	960	19.7%	-6.0 ppts
Net Income	519	9.3%	604	11.6%	-2.3 ppts	724	14.9%	-5.6 ppts
Attributable to:								
Owners of the parent	473		577		-18.0%	724		-34.7%
Basic EPS(NTS)	4.28		5.23		(0.95)	6.71		(2.43)
Weighted-average outstanding shares(M)	110.64		110.37			107.91		

Balance Sheets & Key Indices

(NTD in millions)	1Q26		4Q25		1Q25	
Cash, Current financial assets	8,673	29%	8,031	28%	9,760	41%
Accounts Receivable	2,120	7%	1,503	5%	1,840	8%
Inventory	4,800	16%	4,430	16%	4,032	17%
Long-term Investments	342	1%	313	1%	528	2%
Property, plant and equipment	10,552	35%	10,334	37%	5,891	25%
Intangible assets	1,554	5%	1,572	6%	35	0%
Total Assets	30,215	100%	28,229	100%	23,575	100%
Accounts Pabable	2,063	7%	1,434	5%	1,521	6%
Bank borrowings	5,119	17%	3,683	13%	1,653	7%
Bonds Pabable	-	0%	-	0%	301	1%
Current Liabilites	10,971	36%	8,026	28%	6,628	28%
Total Liabilities	12,836	42%	10,269	36%	8,898	38%
Total Shareholders' Equity	17,379	58%	17,960	64%	14,677	62%
Key Indices						
AR Turnover Days	30		28		33	
Days Sales of Inventory	103		101		105	
AP Turnover days	38		37		42	
Cash Cycle	95		92		96	
Current Ratio(X)	1.50		1.83		2.41	

Cash Flows

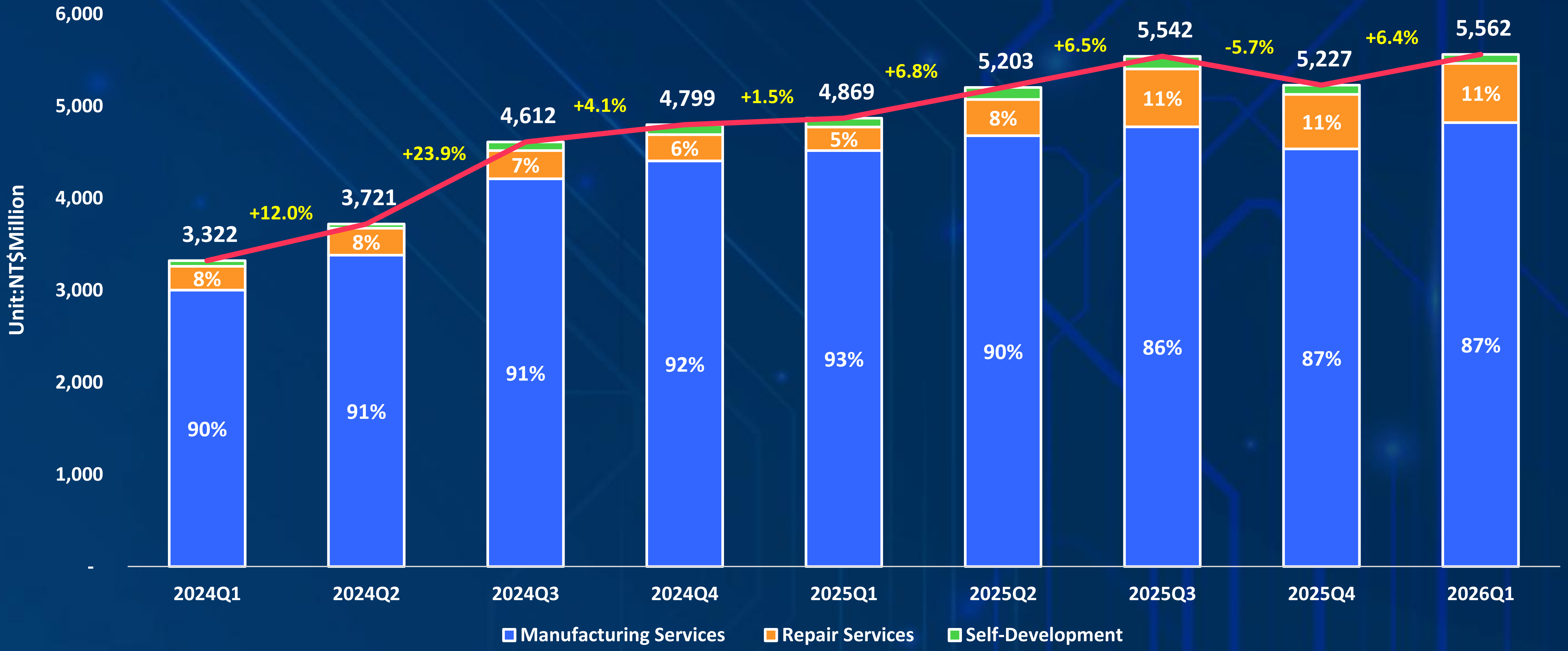
(NTD in millions)	1Q26	1Q25
Beginning Balance	6,626	7,527
Cash from operating activities	111	218
Capital expenditures	(1,078)	(674)
Time deposits	331	(225)
Net Change in Debt	1,455	(106)
Others	114	80
Ending Balance	7,559	6,820
Free Cash Flow*	(968)	(457)

*Free Cash Flow=Cash from operating activities-Capital expenditures

Business Performance and Outlook

Consolidated Revenue Trends

- 1Q26 revenue: NT$5.56bn, YoY +14.2%, QoQ +6.4%,reaching an all-time quarterly high.

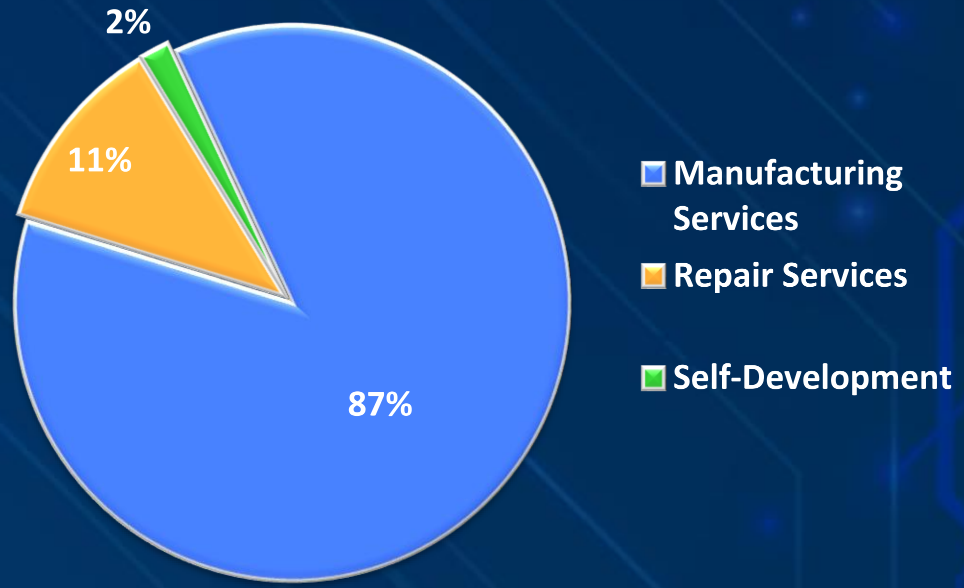


Note:

Manufacturing Services = Semiconductor key modules, key components & spare parts ; Repair Services = Semiconductor & aerospace repair

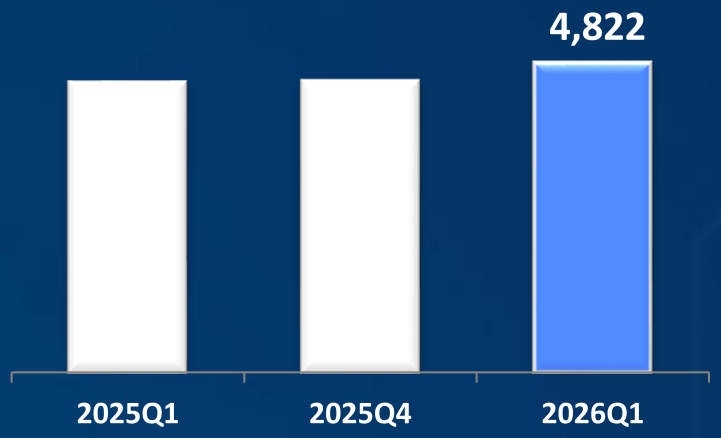
Self-Development = Semiconductor automation equipment

1Q26 Revenues by Business



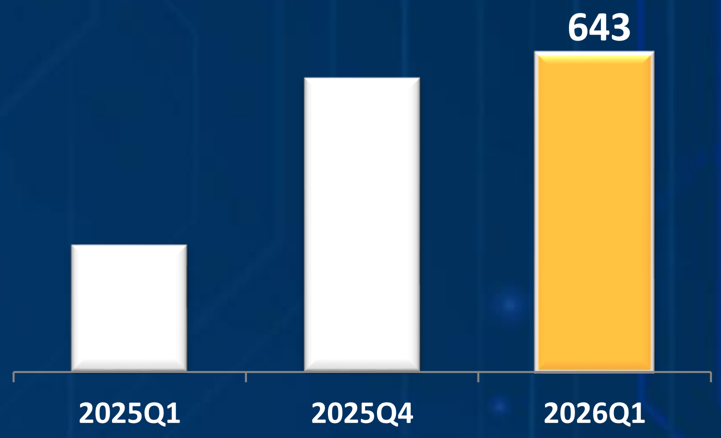
Manufacturing Services
+6.3% QoQ
+6.7% YoY

Unit: NT$M



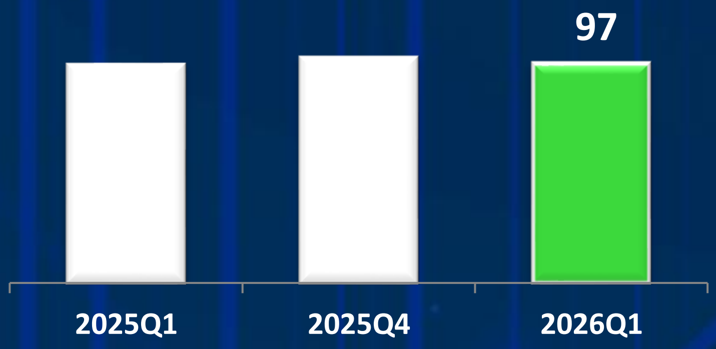
Repair Services
+8.4% QoQ
+151.0% YoY

Unit: NT$M



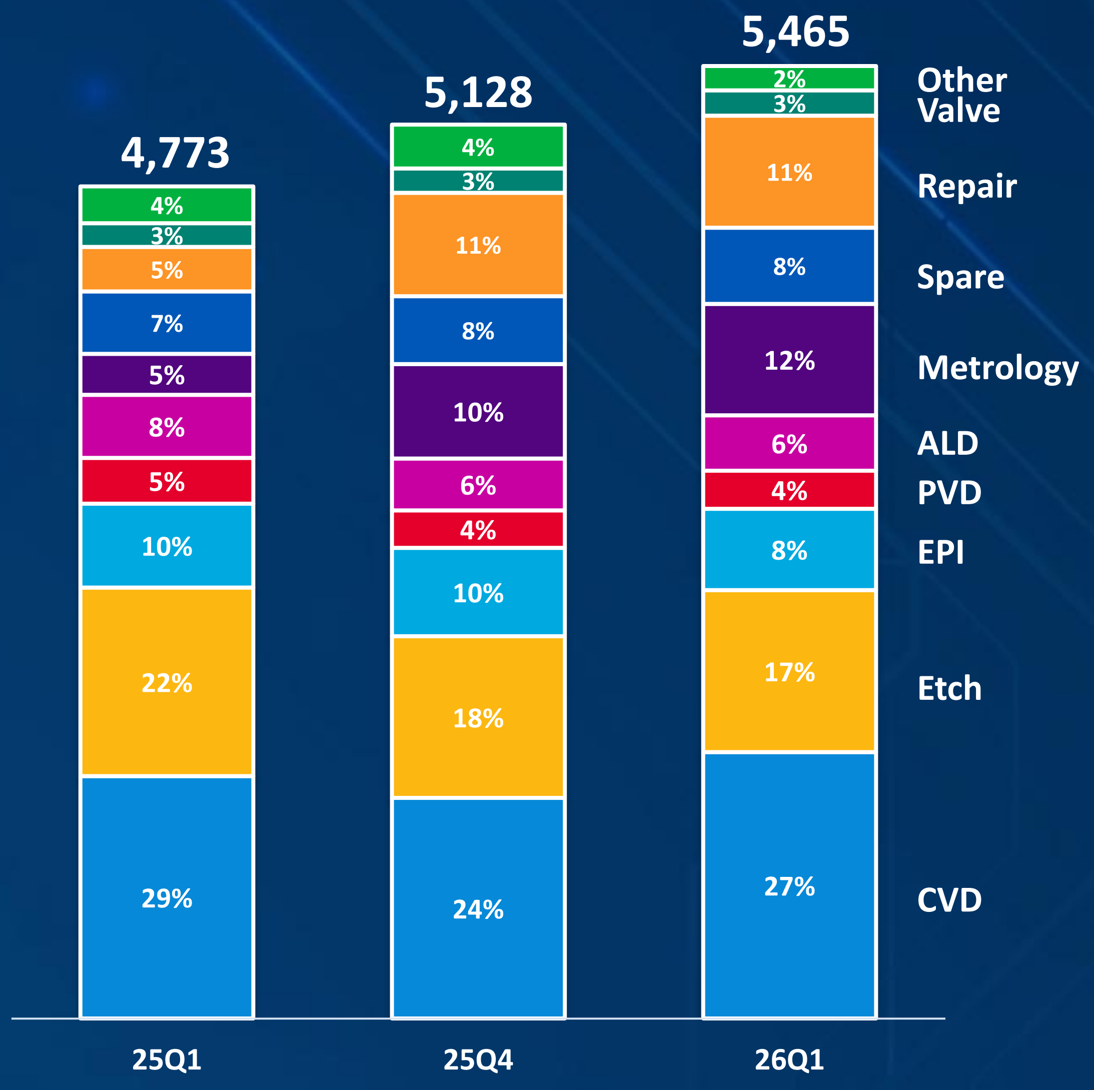
Self-Development
-2.2% QoQ
+0.9% YoY

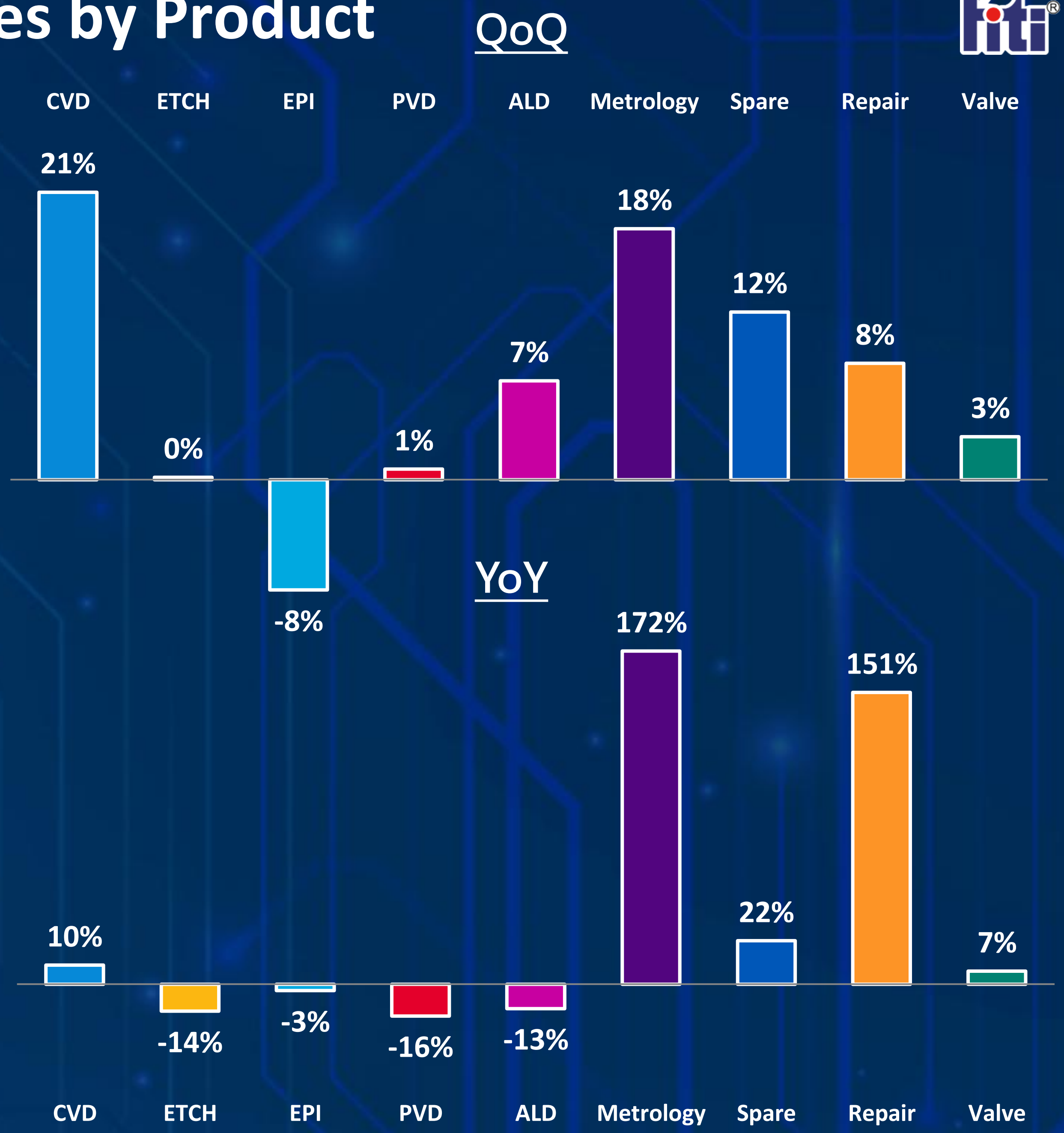
Unit: NT$M



1Q26 Manufacturing & Repair Services by Product

Unit:NT$Million

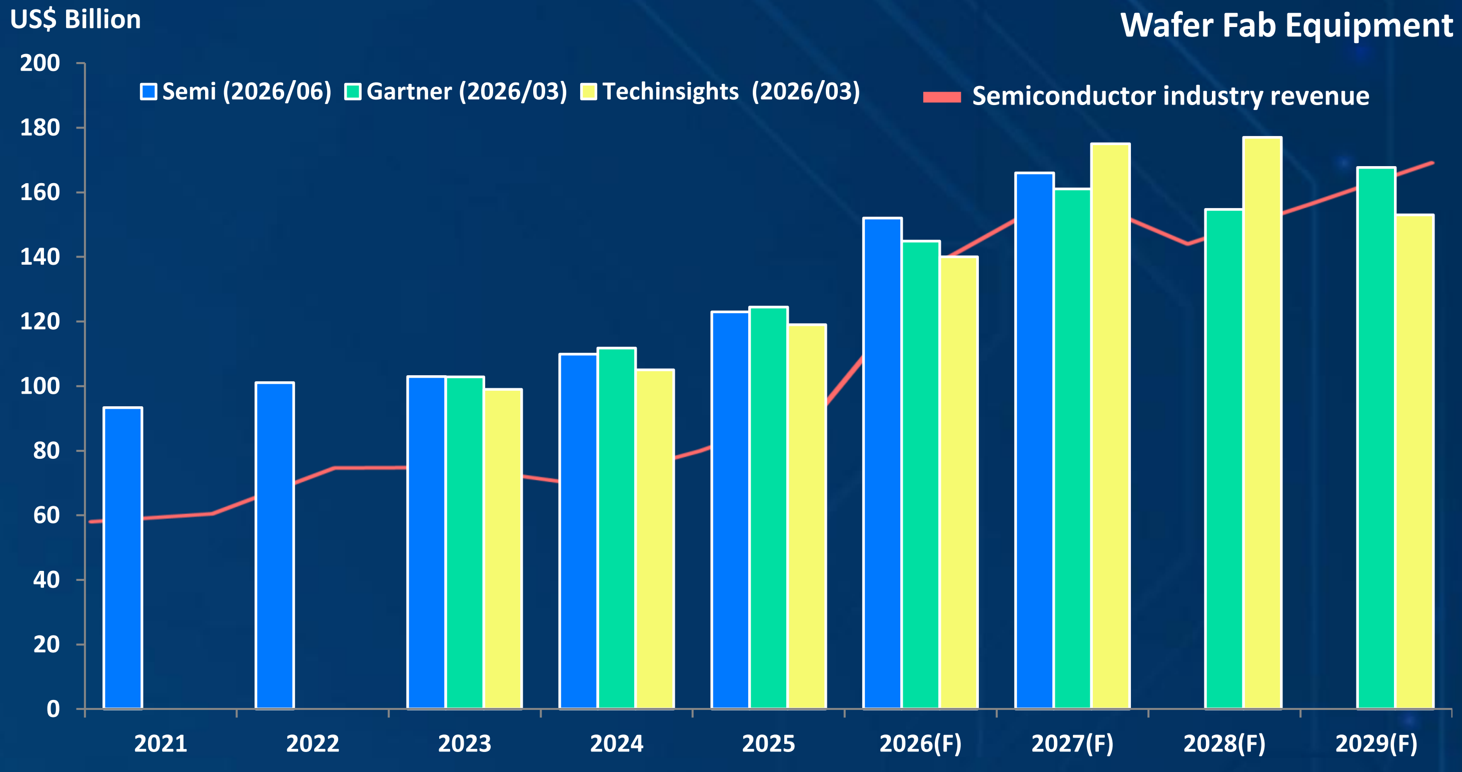




WFE Market

- The WFE market is expected to grow by approximately 18%–24% in 2026, supported by AI-driven investments and continued spending on advanced process technologies, memory, and advanced packaging.
- As fab expansion plans continue to progress, equipment demand visibility continues to extend, supporting industry growth momentum that is expected to continue beyond 2027.
- Over the longer term, the continued advancement of AI applications is driving further development of advanced process technologies and advanced packaging. As semiconductor manufacturing becomes increasingly complex and requires additional process steps, demand for key semiconductor equipment, including etch, deposition, and inspection systems, is expected to continue growing.

Wafer Fab Equipment Spending (WFE)



WFE($B)	2025	2026(F)	2027(F)	2028(F)	2029(F)
Semi (2026/6)	123	152	166		
YoY	12%	24%	9%		
Gartner (2026/3)	124	145	161	155	168
YoY	11%	16%	11%	-4%	8%
TechInsights (2026/3)	119	140	175	177	153
YoY	13%	18%	25%	1%	-14%

Source:Semi/Gartner/TechInsights

FITI's Position in the Semiconductor Equipment Value Chain

Wafer Fabrication						Packaging and Testing	
Deposition	Diffusion	Lithography	Etch	CMP	Metrology	Package	Test

89% Semiconductor Equipment Market

11% Semiconductor Equipment Market

New Technology	GAA	BSPDN	HBM/ NAND	Advanced Packaging	Heterogeneous Integration
2025-2030 Market CAGR	>20%	>20%	>30%/ >20%	>40%	>30%

Source: WSTS 、Nomura

Serving Advanced Wafer Fabrication and Advanced Packaging Markets Through Vertically Integrated Manufacturing

Semiconductor Equipment Lifecycle Manufacturing Services

NPI + Module/ System assembly + Critical Components + Spare Parts + Repair = Vertically Integrated Manufacturing

2Q26 Business Outlook

Fiti	=	Manufacturing Services	+	Repair Services	+	Self-Development
QoQ		QoQ		QoQ		QoQ
YoY		YoY		YoY		YoY

Summary

Key Highlights

- 1Q'26 revenue reached a record quarterly high, with order visibility continuing to improve. Full-year revenue growth is targeted to outperform overall WFE market growth.
- The Chonburi, Thailand facility is expected to gradually ramp up volume production in 3Q'26, providing additional support for future revenue growth and margin expansion.

Long-Term Growth Drivers

- **Expanding Equipment Market:**

  AI and HPC continue to drive structural growth in the global WFE market, supporting increased investments in advanced logic, memory, and advanced packaging. This trend is driving demand for deposition, etch, and inspection equipment in advanced applications.
- **Technology-Driven Equipment Demand:**

  Ongoing advancements in GAA, HBM, and advanced packaging technologies are increasing process complexity, driving sustained demand for critical equipment such as deposition, etch, and inspection systems.
- **Continued Product Diversification:**

  Demand for existing products remains strong, while new product introduction (NPI) programs continues to expand, reinforcing a clear dual-engine strategy.

Q&A

Thank you